

Elevating Automation for THT Component Inspection

With the rapid progression of labor-saving measures in the PCB manufacturing field, demand for improved product quality and faster automation increases, even in the back-end inspection process. SAKI achieves premium quality assurance and automation of the THT component inspection process with 3D-AOI and 3D-CT AXI.



Inspection Challenges for THT Components

- Height measurement range limitations
- Superior QA for THT component solder inspection
- FOD on the PCB surface (solder balls or extra components)
- Meeting IPC standards for solder inspection

Unlocking SAKI's 3 Key Solutions

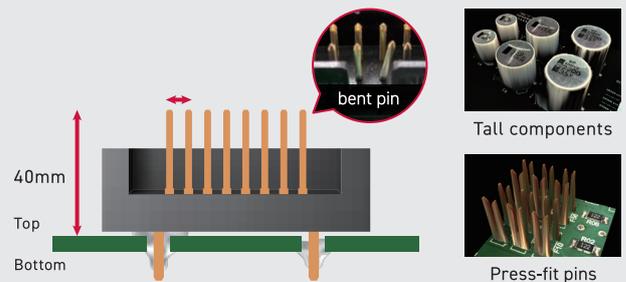
3D-AOI THT Component Inspection

Advanced Z-axis Solution*

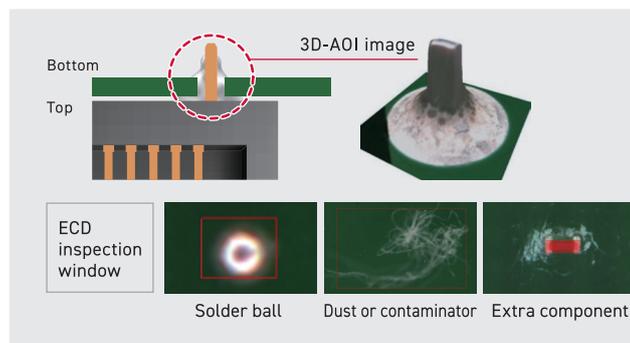
Improved height measurement range extends to 40mm, allowing for comprehensive height and character inspection of tall components.

New Connector Pin Inspection Algorithm

Wider inspection coverage is provided for pin pitch and height measurements, bent pins, abnormal height, and increasingly-important press-fit pin inspection.



*Z-axis solution optional.



3D-AOI THT Solder Inspection

New 3D Solder Inspection Algorithm

SAKI's proprietary Fujiyama algorithm performs inspection in a single step for pin height, copper exposure, hole, pin detection, soldering fillet, insufficient solder, and automatic bridge area recognition.

Extra Component Detection (ECD) Inspection Capability

ECD detects solder balls and foreign objects without needing a sample board; the entire PCB can be inspected from height threshold information alone.

3D-AXI THT Solder Inspection

SAKI's Unique Planar CT Technology

Advanced software achieves high-speed and high-definition 3D image capture.

Dedicated PTH Algorithm

- SAKI's unique inspection algorithm quantitatively inspects the solder amount (filling rate) and volume inside the through-hole. [Compliant with IPC standards]
- Pin bridge inspection is also available.

